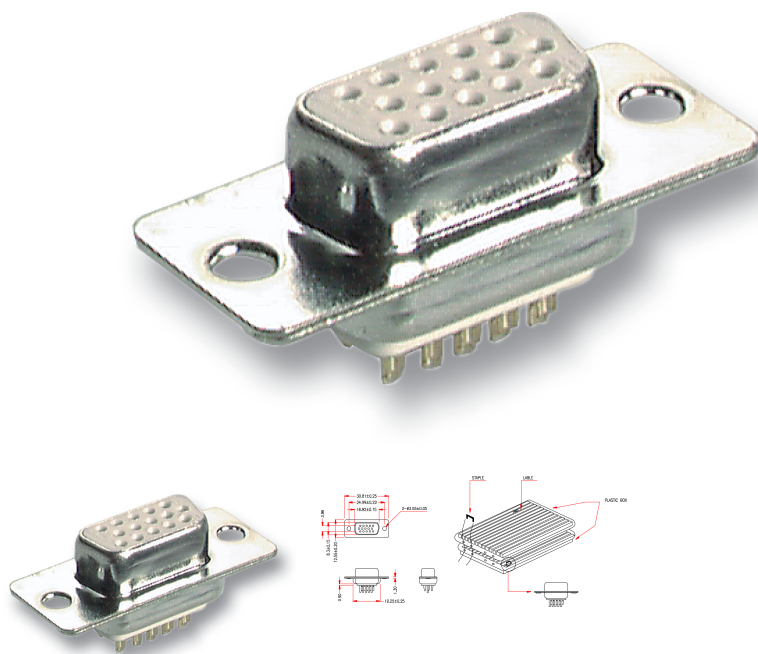


DATASHEET

HD-DSub Solder Jack E-HDF 15 LL/Z



General data

The HD D-Sub 15 pol. Soldering socket from EFB-Elektronik is designed for a reliable solder connection on the printed circuit board. With a 180° connection angle and female contact design, it is suitable for compact connectors in applications with round or flat cables.

- 15-pin HD D-Sub solder socket for PCB mounting
- 180° design with solder connection for a stable connection
- Female contact design for suitable connectors

Due to the temperature range of -40 to 70 °C, the socket is designed for typical technical environments. The E-HDF 15 LL/Z version supports a resilient signal connection in applications where a compact and permanently reliable interface is required.

Technical details

- Type: E-HDF 15 LL/Z
- Connection type: Soldering
- Shooting angle: 180°
- Finish: Socket
- For cable type: round/flat
- Contact version: female
- Conductor cross-section: 34AWG ~ 22AWG
- Number of poles: 15

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DATASHEET

HD-DSub Solder Jack E-HDF 15 LL/Z

- Temperature range: -40 – 70 °C
- Brand: EFB-Elektronik
- Packaging: 50 pieces per blister

Technical properties

Conductor cross-section	34AWG ~ 22AWG
Connection angle (180°/90°)	180
Connection type	Solder
Contact manufacturing method (turned/stamped)	stamped
Contact type	female
For cable type (round/flat)	round/flat
Model	jack
Temperature range	-40 – 70

Available variants

ArtNr.	Bezeichnung	Number of poles	Type	Packaging	Numbrt of rows
34501.1	HD-DSub Solder Jack E-HDF 15 LL/Z	15	E-HDF 15 LL/Z	50 pieces per tray	3
34510.1	HD-DSub Solder Jack E-HDF 26 LL/Z	26	E-HDF 26 LL/Z	50 pieces per tray	3

Note on Intended Use

This data sheet is intended solely to describe the technical characteristics of the product. It does not replace an assessment of the product's suitability for a specific application. The user is responsible for ensuring that the product is used in accordance with its technical specifications and applicable legal and regulatory requirements.

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